

### General Description

These N-channel enhanced vdmofets, is obtained by the self-aligned planar technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. Which accords with the RoHS standard.

Product Summary			
V <sub>DS</sub>	R <sub>DS(on)</sub> (Ω) Typ	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)
800V	1.5 @ 10V, 3.5A	7	34nc

### Features

- Low on-resistance
- Low reverse transfer capacitance
- 100% avalanche tested

### Mechanical Data

- Case: ITO-220 Package



### Application

- LED power switch circuit
- Electronic ballast
- Switch mode power supply
- Electronic transformer

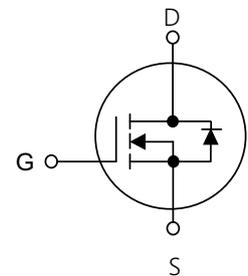
### Ordering Information

Part No.	Marking.	Package Type	Package	Quality(box)
7N80F	7N80F	ITO-220	Tube	1000

Pin Definition:

1. Gate
2. Drain
3. Source

### Block Diagram



**Table1 Absolute Maximum Ratings** (T<sub>c</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	800	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current	I <sub>D</sub>	T <sub>c</sub> =25°C	7
		T <sub>c</sub> =100°C	4.2
Pulsed Drain Current (Note 1)	I <sub>DM</sub>	28	A
Single Pulse Avalanche Energy(Note 2)	E <sub>AS</sub>	466	mJ
Power Dissipation T <sub>c</sub> =25°C	P <sub>D</sub>	33	W
Operating Junction and Storage Temperature	T <sub>J</sub> /T <sub>STG</sub>	-55~+150	°C

**Table 2. Thermal Characteristics**

Parameters	Symbol	Value	Unit
Thermal resistance Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$
Thermal resistance Junction to Case	$R_{\theta JC}$	3.8	$^{\circ}\text{C}/\text{W}$

**Table 3. Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	800	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=800V, V_{GS}=0V$	-	-	25	$\mu\text{A}$
Gate- Source Leakage Current	Forward	$V_{GS}=30V, V_{DS}=0V$	-	-	100	nA
	Reverse	$V_{GS}=-30V, V_{DS}=0V$	-	-	-100	nA
On Characteristics(Note 3)						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	-	4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.5A$	-	1.5	1.8	$\Omega$
Dynamic Characteristics(Note 4)						
Input Capacitance	$C_{ISS}$	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	-	1443	-	pF
Output Capacitance	$C_{OSS}$		-	118	-	pF
Reverse Transfer Capacitance	$C_{RSS}$		-	11.2	-	pF
Switching Characteristics (Note 4)						
Turn-On Delay Time	$t_d(\text{on})$	$V_{DD}=400V, I_D=7A$ $R_G=10\Omega, V_{GS}=10V$	-	21	-	ns
Turn-On Rise Time	$t_r$		-	17	-	ns
Turn-Off Delay Time	$t_d(\text{off})$		-	50	-	ns
Turn-Off Fall Time	$t_f$	$V_{DS}=640V, I_D=7A,$ $V_{GS}=10V$	-	21	-	ns
Total Gate Charge	$Q_G$		-	34	-	nC
Gate-Source Charge	$Q_{GS}$		-	6.7	-	nC
Gate-Drain Charge	$Q_{GD}$		-	16	-	nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=7A$	-	-	1.5	V
Maximum Continuous Drain-Source Diode Forward Current	$I_S$		-	-	7	A
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_F=7A$	-	626	-	ns
Reverse Recovery Charge	$Q_{RR}$	$dI_F/dt=100A/\mu\text{s}$ (Note 1)	-	4990	-	nC

Notes : 1 Repetitive Rating:Pulse width limited by maximum junction temperature

2  $L=10\text{mH}, I_D=9.7A, V_{DD}=50V, \text{Starting } T_J=25^{\circ}\text{C}$

3 Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$

4 Guaranteed by design, not subject to production

Typical Characteristics Diagrams

Figure 1. Output Characteristics

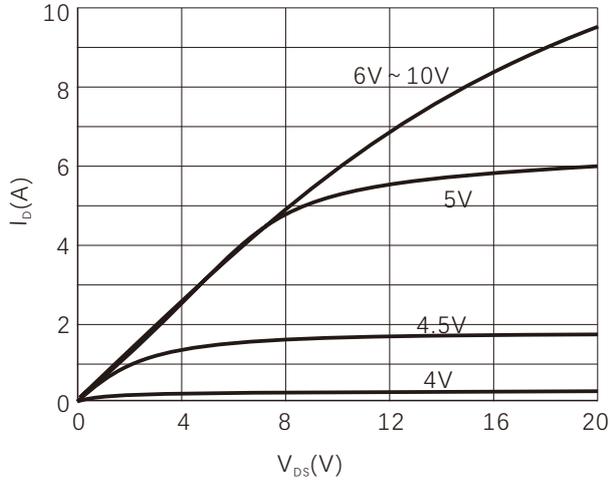


Figure 2.  $R_{DS(on)}$  vs Junction Temperature

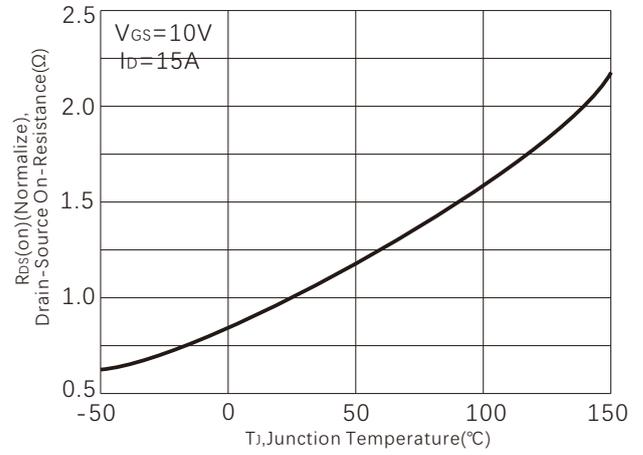


Figure 3. On-Resistance vs. Drain Current

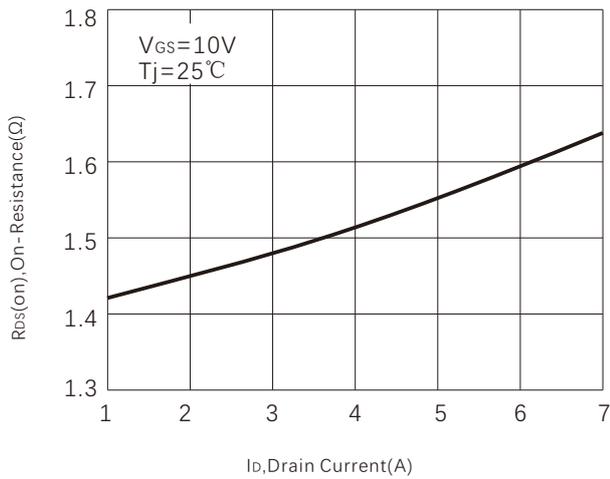


Figure 4. Capacitance

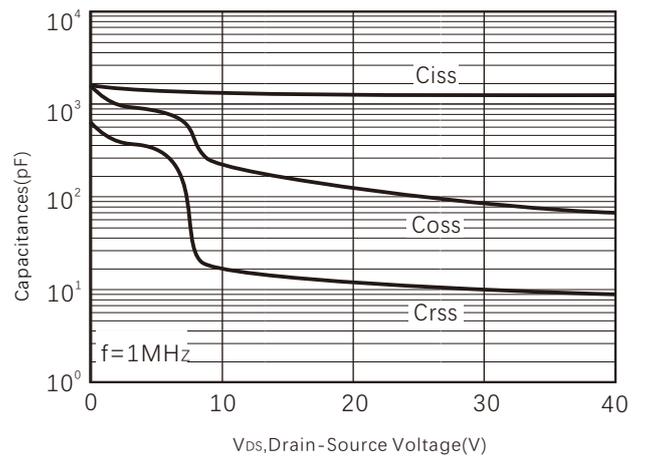


Figure 5. Gate charge

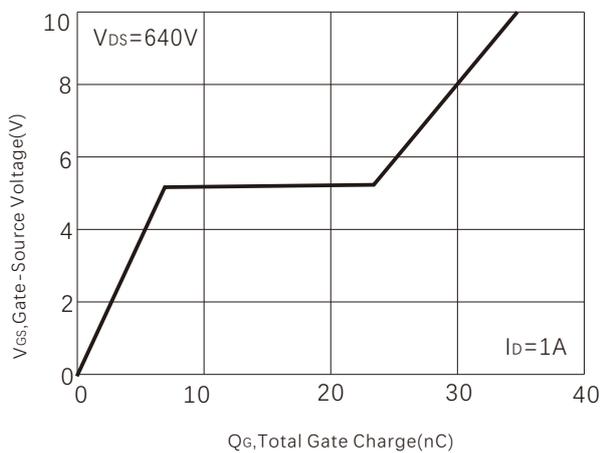


Figure 6. Source-Drain Diode Forward Voltage

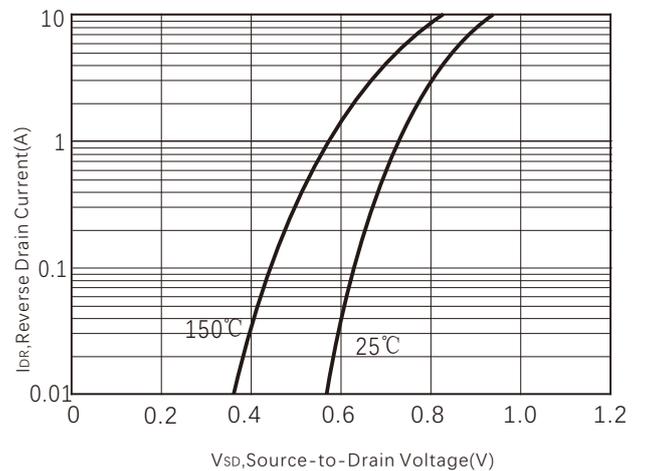


Figure 7. Maximum Drain Current vs Temperature

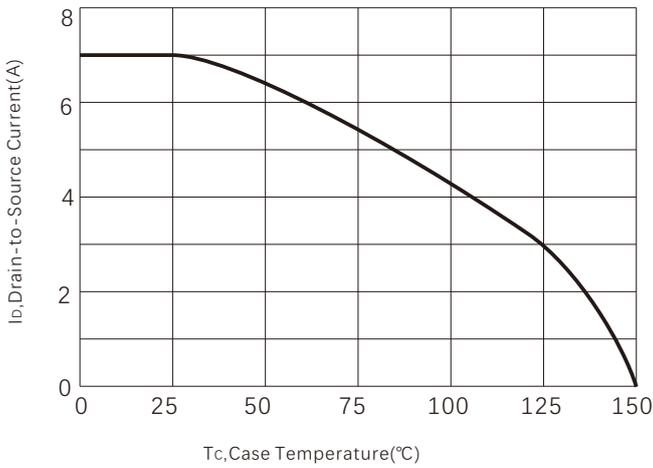


Figure 8. Power dissipation

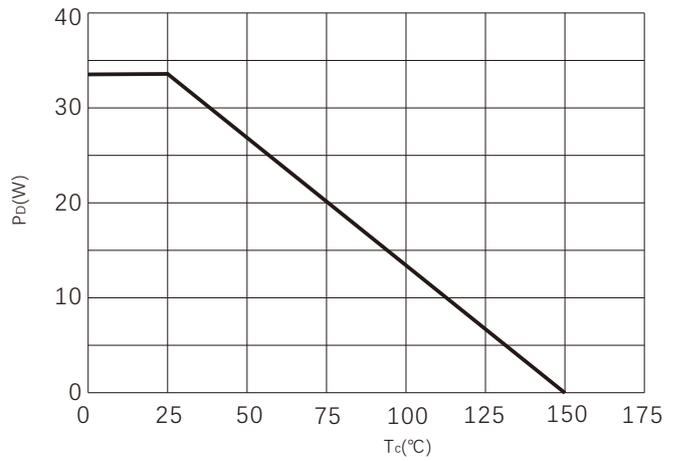


Figure 9.

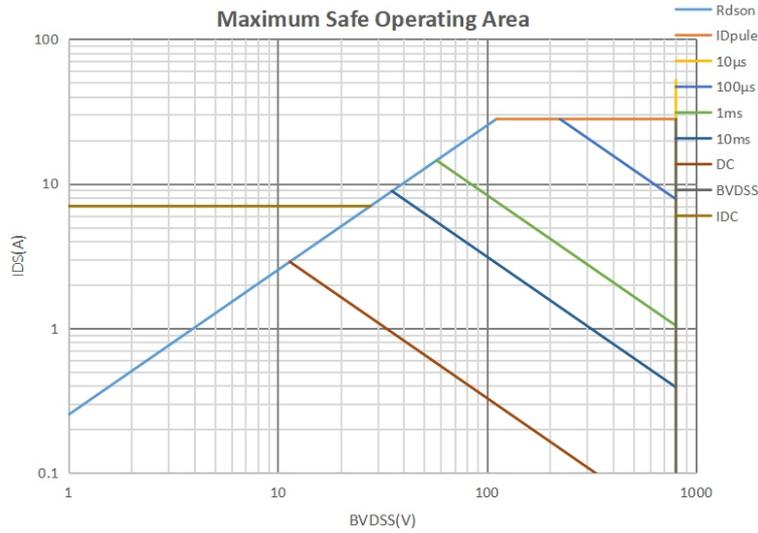
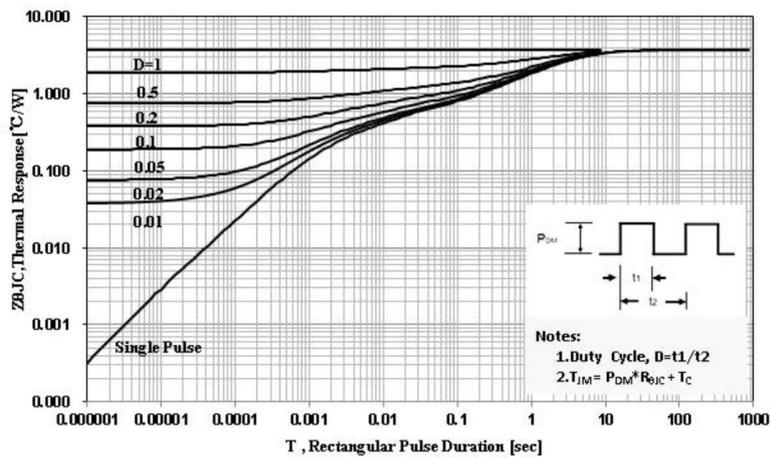
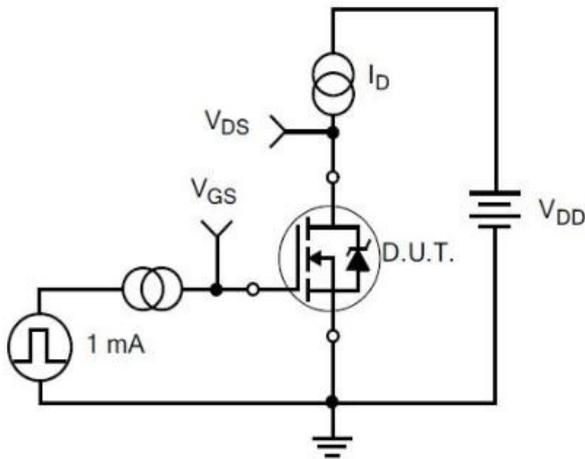


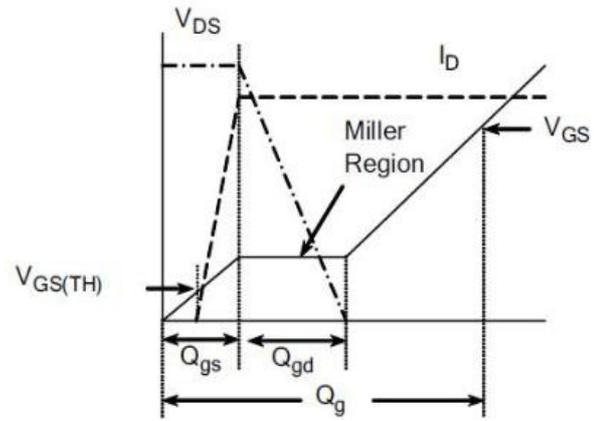
Figure 10. Maximum Transient Thermal Impedance



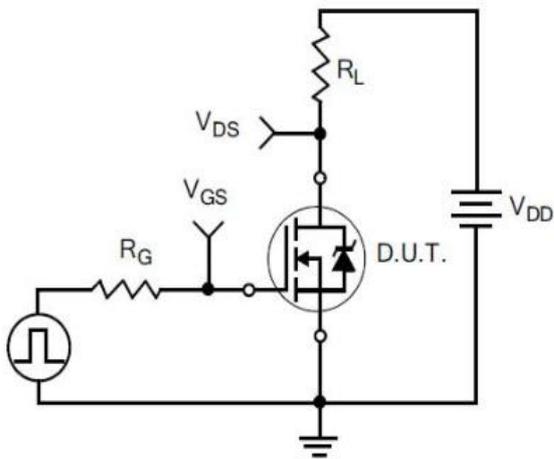
Typical Test Circuit



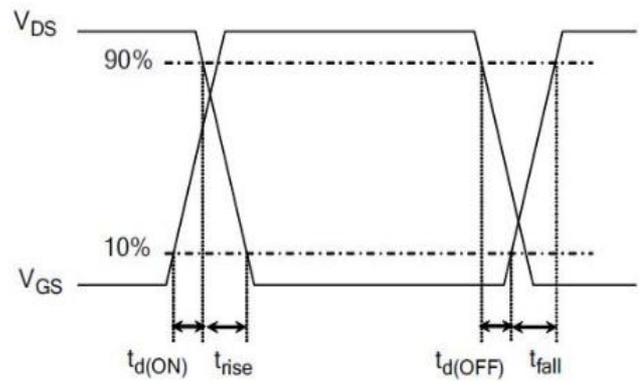
1) Gate Charge Test Circuit



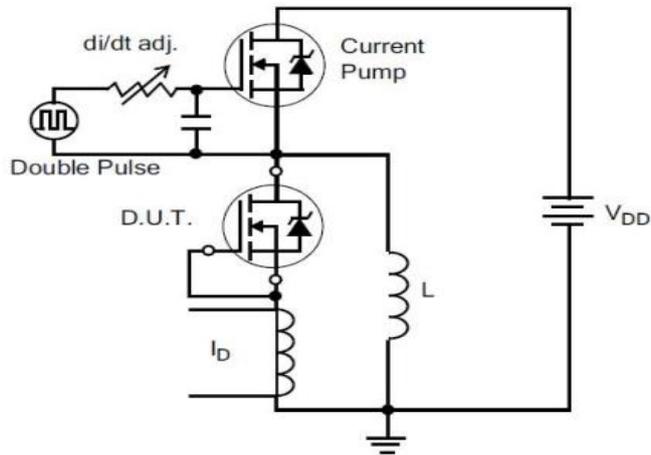
2) Gate Charge Waveform



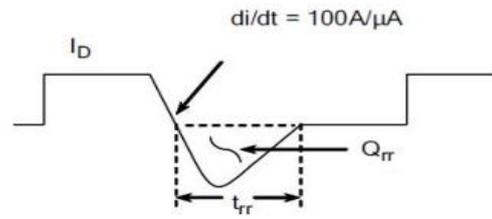
3) Resistive Switching Test Circuit



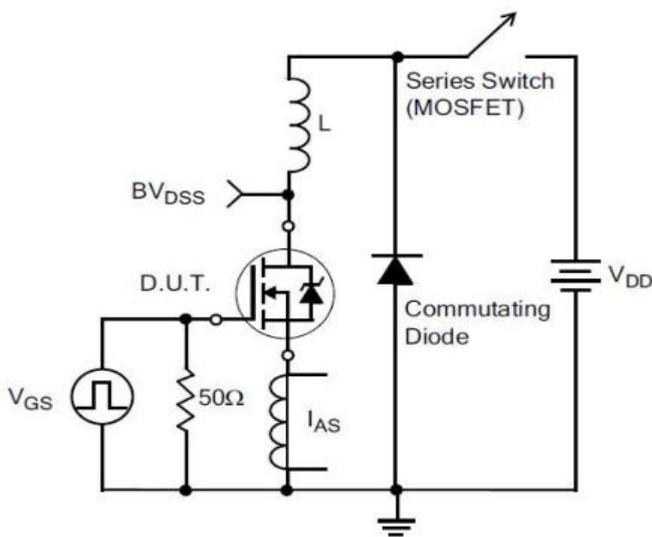
4) Resistive Switching Waveforms



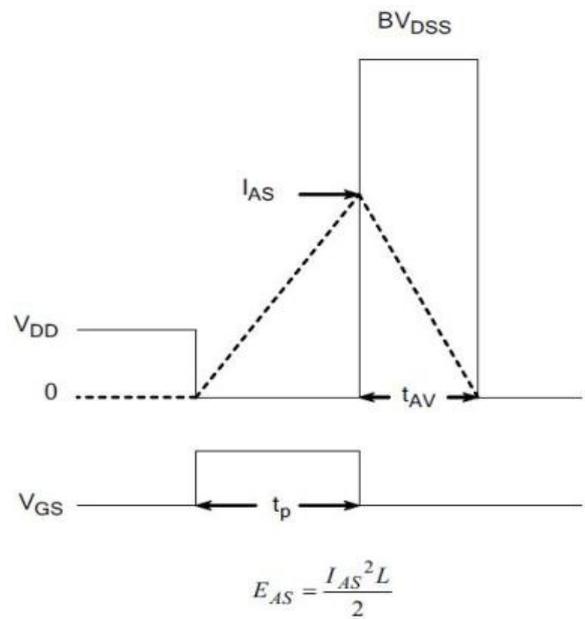
5) Diode Reverse Recovery Test Circuit



6) Diode Reverse Recovery Waveform



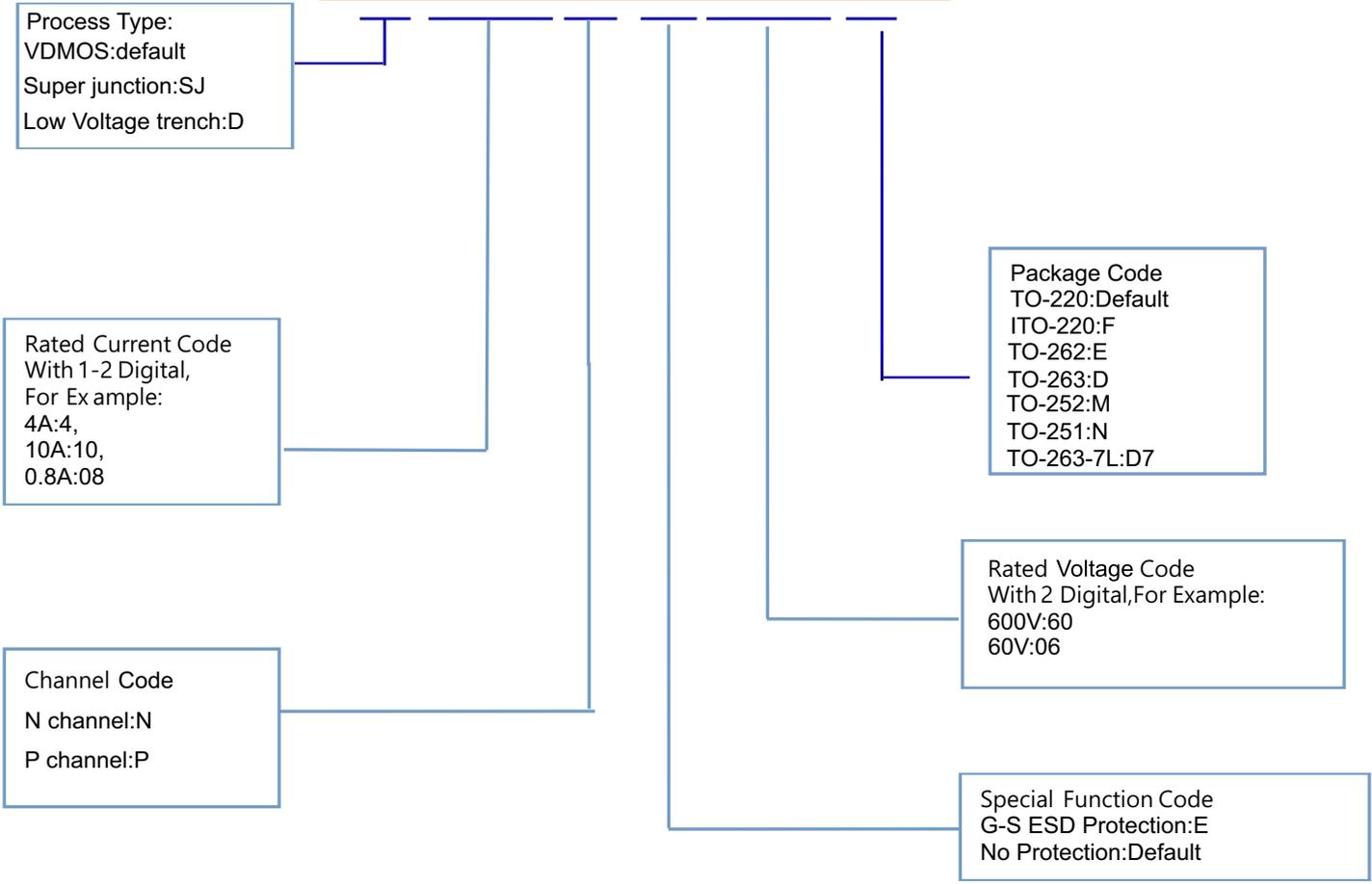
7) . Unclamped Inductive Switching Test Circuit



8) Unclamped Inductive Switching Waveforms

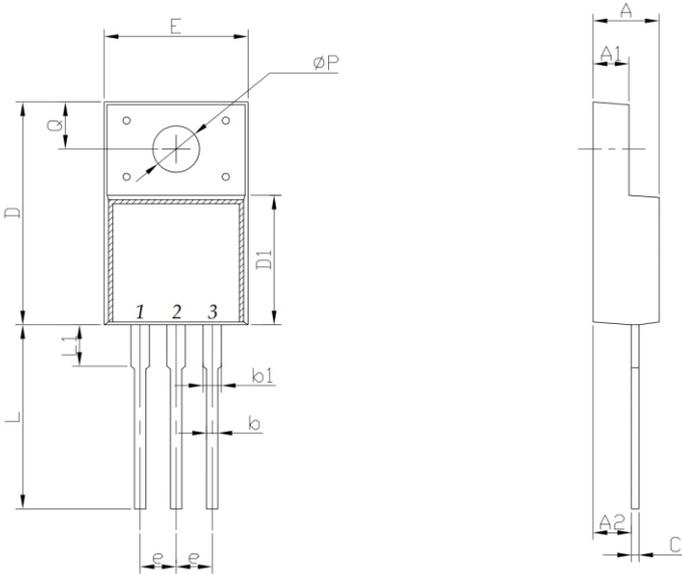
Product Names Rules

X X X N E X X X



Dimensions

ITO-220 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	4.24	4.9	0.167	0.193
A1	2.3	2.92	0.091	0.115
A2	2.61	2.81	0.103	0.111
b	0.3	1	0.012	0.039
b1	0.9	1.55	0.035	0.061
C	0.3	0.7	0.012	0.028
D	14.5	16.36	0.571	0.644
D1	8.8	9.41	0.346	0.370
E	9.5	10.5	0.374	0.413
e	2.3	2.75	0.091	0.108
L	12.6	14	0.496	0.551
L1	2.45	4.3	0.096	0.169
P	2.9	3.8	0.114	0.150
Q	2.5	3.55	0.098	0.140

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